

PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Taiji Ema	02/25/2011
RECEIVING PARTY DATA	
Name:	Fujitsu Semiconductor Limited, Inc.
Street Address:	Nomura Fudosan, Shin-Yokohama Building
Internal Address:	2-10-23 Shin-Yokohama, Kohoku-ku Yokohama
City:	Kanagawa
State/Country:	JAPAN
Postal Code:	222-0033
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12895657
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ATTORNEY DOCKET NUMBER:	078023.0346 (10-011)
NAME OF SUBMITTER:	Judy Baggett
Total Attachments: 2 source=10011assignitofuj#page1.tif source=10011assignitofuj#page2.tif	

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PATENT
REEL: 025926 FRAME: 0720

ASSIGNMENT

WHEREAS, I, an undersigned joint inventor of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, said application having been executed on the date set forth below; and

WHEREAS, **Fujitsu Semiconductor Limited, Inc.** (hereafter referred to as "Assignee"), having an address of Nomura Fudosan Shin-Yokohama Building, 2-10-23 Shin-Yokohama, Kohoku-ku, Yokohama, Kanagawa 222-0033, JAPAN, desires to acquire my entire right, title, and interest in and to the invention and in and to the said application and any Letters Patent that may issue therefrom;

NOW, THEREFORE, for and in consideration of One United States Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I assign to Assignee, all right, title, and interest in and to said invention and in and to said application, all patents that may issue therefrom, and all divisions, reissues, continuations, continuations-in-part and extensions thereof. I hereby authorize and request the Commissioner of Patents and Trademarks to issue all patents for said invention, or patents resulting therefrom, insofar as my interest is concerned, to Assignee.

I also assign to Assignee, all right, title, and interest in and to the invention disclosed in said application throughout the world, including the right to file applications and obtain patents, utility models, industrial models, and designs for said invention in its own name throughout the world and including all rights to publish cautionary notices reserving ownership of said invention and all rights to register said invention in appropriate registries agree to execute any and all powers of attorney, applications, assignments declarations, affidavits, and any other papers in connection therewith that may be necessary to perfect such right, title, and interest in Assignee.

I shall communicate to Assignee any facts known to me with respect to any improvements; and, at the expense of Assignee, I shall testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, continuation-in-part, reissue, and substitute applications, make lawful oaths and declarations, and generally do everything possible to vest title in Assignee and to aid Assignee to obtain and enforce proper protection for said invention in all countries.

This Assignment shall be binding on the parties' successors, assigns, and legal representatives.

ATTORNEY DOCKET NO.
078023.0346
(10-011)

ASSIGNMENT

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Title of Invention:

*METHOD FOR MINIMIZING DEFECTS IN A
SEMICONDUCTOR SUBSTRATE DUE TO ION
IMPLANTATION*

Signature of Inventor:
Full name of inventor:

Taiji Ema
Taiji Ema

Residence:

Toin-cho, Inabe-gun, Mie-ken, Japan 511-0233

Date:

2011/2/25